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Specification for Approval

Customer:	
Model Name:	

Sı	Customer approval		
R&D Designed	R&D Approved	QC Approved	
Peter	Peng Jun		

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Revision Record

REV NO.	REV DATE	CONTENTS	Note
Α	2017-03-03	NEW ISSUE	
В	2018-09-05	MODIFY VIEWING	

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1. Scope

This specification defines general provisions as well as inspection standards for TFT module supplied by AMSON electronics.

If the event of unforeseen problem or unspecified items may occur, naturally shall negotiate and agree to solution.

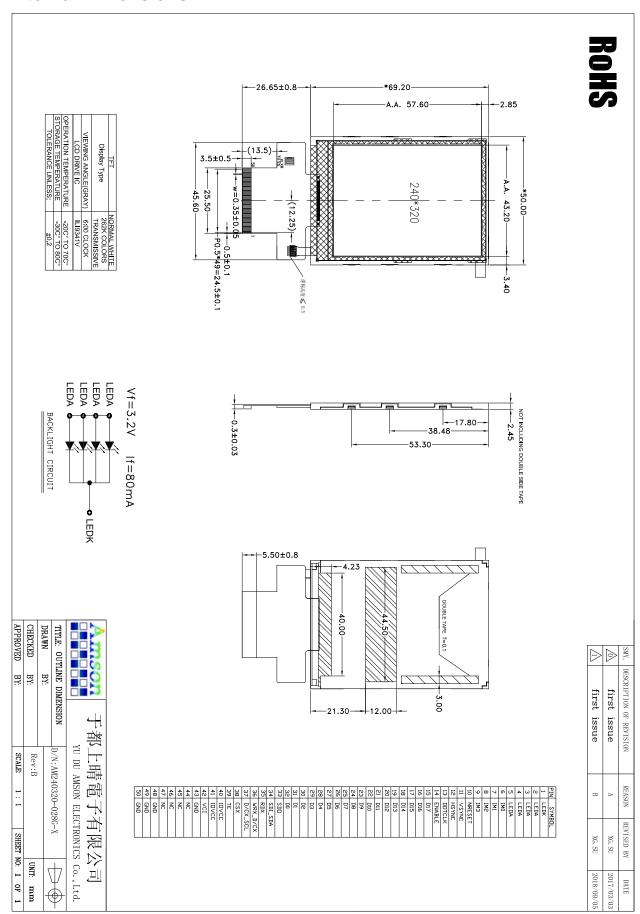
2. General Information

ITEM	STANDARD VALUES	UNITS
LCD type	2.8"TFT	
Dot arrangement	240(RGB)×320	dots
Color filter array	RGB vertical stripe	
Display mode	TN / Transmission / Normally White	
Gray scale inversion Direction	6 o'clock	
Viewing Direction	12 o'clock	
Driver IC	ILI9341V	
Module size	50.0(W)×69.2(H)×2.45(T)	mm
Active area	43.2(W)×57.6(H)	mm
Dot pitch	0.18(W)×0.18(H)	mm
Interface	4-lines_8bit / 3-lines_9bit SPI 8-/ 9-/16-/18-bit 8080-series system interface 6-/16-/18-bit RGB interface	
Operating temperature	-20 ~ +70	°C
Storage temperature	-30 ~ +80	°C
Back Light	4 White LED In Parallel	
Weight	TBD	g

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3. External Dimensions





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4. Interface Description

4. 1	nterface D	escription					
Pin	Symbol	Description.					
1	LEDK	LED backlight (Cathode).					
2	LEDA	LED backlight (Anode).					
3	LEDA	LED backlight (Anode).					
4	LEDA	LED backlight (Anode).					
5	LEDA	LED backlight (Anode).					
		System interface Mode					
6	IMO	IM3 IM2 IM1 IM0 Interface mode DB Pin					
		0 0 0 i80-system 8-bit interface I DB[7:0]					
		0 0 1 i80-system 16-bit interface I DB[15:0] 0 0 1 0 i80-system 9-bit interface I DB[8:0]					
7	IM1	0 0 1 1 i80-system 18-bit interface I DB[8:0]					
		0 1 0 1 3-wires_9-bit SPI I CSX,SDA,SCL					
		0 1 1 0 4-wires_8-bit SPI I CSX,RS,SDA,SCL					
8	IM2	1 0 0 0 i80-system 16-bit interface Ⅱ DB[17:10],DB[8:1]					
		1 0 0 1 i80-system 8-bit interface Ⅱ DB[17:10]					
		1 0 1 0 i80-system 18-bit interface II DB[17:0]					
9	IM3	1 0 1 1 i80-system 9-bit interface					
		1 1 1 0 4-wires_8-bit SPI II CSX,D/CX,SDI,SDO,SCL					
10	NRESET	Reset input pin, Active "L".					
11	VSYNC	Vertical sync signal in RGB I/F.					
12	HSYNC	Horizontal sync signal in RGB I/F.					
13	DOTCLK	Pixel clock signal in RGB I/F.					
14	ENABLE	Data enable signal in RGB I/F mode					
15	D17						
16	D16						
17	D15	18-bit parallel bi-directional data bus for MPU- I system:					
18	D14	8-bit I/F: DB [7:0] is used.					
19	D13	9-bit I/F: DB [8:0] is used.					
20	D12	16-bit I/F: DB [15:10] is used. 18-bit I/F: DB [17:0] is used.					
21	D11						
22	D10	18-bit parallel bi-directional data bus for MPU- II system:					
23	D9	8-bit I/F: DB [17:10] is used.					
24	D8	9-bit I/F: DB [17:9] is used. 16-bit I/F: DB [17:10] and DB [8:1] is used.					
25	D7	18-bit I/F: DB [17:0] is used.					
26	D6	40 L W					
27	D5	18-bit input data bus for RGB I/F. 6-bit/pixel: DB[5:0] is used;					
28	D4	0-bit/pixel: DB[3:0] is used, 16-bit/pixel: DB[17:13]=R[4:0], DB[11:6]=G[5:0] and DB[5:1]=B[4:0];					
29	D3	18-bit/pixel: DB[17:12]=R[5:0], DB[11:6]=G[5:0] and DB[5:0]=B[5:0];					
30	D2	Connect unused pins to GND.					
31	D1						
32	D0						



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33	SDO	Serial output signal in SPI I/F.
34	SDI_SDA	Serial input signal in SPI I/F.
35	RDX	Reads strobe signal to write data when RDX is "Low" in MPU interface.
36	WRX_D/CX	MCU: Serves as a write signal and writes data at the rising edge. 4-line SPI: Serves as command or parameter select.
37	D/CX_SCL	Display data / command selection in 80-series MPU I/F. D/CX ="0": Command D/CX ="1": Display data. SPI: This pin is used serial interface clock in SPI.
38	CSX	Chip select input pin ("Low" enable) in MPU I/F and SPI I/F.
39	TE	Tearing effect output pin to synchronize MPU to frame writing.
40	IOVCC	I/O power supply.
41	IOVCC	I/O power supply.
42	VCI	System power supply.
43	GND	Power ground
44	NC	
45	NC	No compation
46	NC	No connection
47	NC	
48	GND	Power ground
49	GND	Power ground
50	GND	Power ground

5. Absolute Maximum Ratings

. Absolute maximum Natings								
Item	Symbol	Min.	Max.	Unit				
Logic Supply Voltage	IOVCC	-0.3	4.6	V				
Analog Supply Voltage	VCI	-0.3	4.6	V				
Input Voltage	Vin	-0.3	IOVCC+0.3	V				
Operating Temperature	Тор	-20	70	°C				
Storage Temperature	Тѕт	-30	80	°C				
Storage Humidity	HD	20	90	%RH				

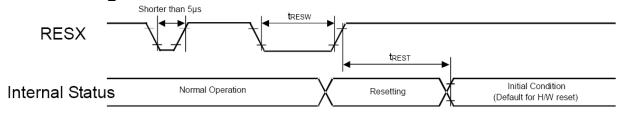
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6. DC Characteristics

Item	Symbol	Min.	Тур.	Max.	Unit	Remark
Logic Supply Voltage	IOVCC	1.65	1.8/2.8	3.3	٧	-
Analog Supply Voltage	VCI	2.5	2.8	3.3	٧	-
Input High Voltage	V _{IH}	0.7IOVCC	-	IOVCC	٧	Digital input pins
Input Low Voltage	V _{IL}	GND	ı	0.3IOVCC	V	Digital input pins
Output High Voltage	V _{OH}	0.8IOVCC	ı	IOVCC	>	Digital output pins
Output Low Voltage	V_{OL}	GND	1	0.2IOVCC	>	Digital output pins
I/O Leak Current	lLı	-0.1	-	0.1	uA	-

7. Timing Characteristics7.1 Reset Timing Characteristics

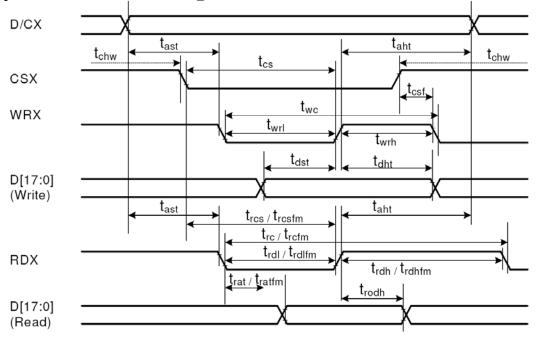


Symbol	Parameter	Related pins	Min.	Тур.	Max.	Note	Unit
t _{RESW}	Reset low pulse width ⁽¹⁾	RESX	10	-	- 4	-	μs
+	Reset complete time ⁽²⁾	-	5	- <	(O)	When reset is applied during Sleep In mode	ms
ι _{REST}	Reset complete time	1	120	3		When reset is applied during Sleep Out mode	ms

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7.2 i80-System Interface Timing Characteristics

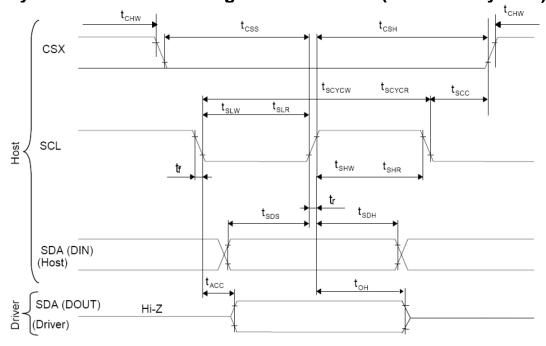


Signal	Symbo I	Parameter	min	max	Unit	Description
Dov tast		Address setup time	0	-	ns	
DCX	taht	Address hold time (Write/Read)	0	-	ns	
	tchw	CSX "H" pulse width	0	-	ns	
	tcs	Chip Select setup time (Write)	15	-	ns	
CSX	trcs	Chip Select setup time (Read ID)	45	-	ns	
	trcsfm	Chip Select setup time (Read FM)	355	-	ns	
	tcsf	Chip Select Wait time (Write/Read)	10	-	ns	
	twc	Write cycle	66	-	ns	
WRX	twrh	Write Control pulse H duration	15	-	ns	
	twrl	Write Control pulse L duration	15	-	ns	
	trcfm	Read Cycle (FM)	450	-	ns	
RDX (FM)	trdhfm	Read Control H duration (FM)	90	-	ns	
	trdlfm	Read Control L duration (FM)	355	-	ns	
	trc	Read cycle (ID)	160	-	ns	
RDX (ID)	trdh	Read Control pulse H duration	90	-	ns	
	trdl	Read Control pulse L duration	45	-	ns	
D[47.0]	tdst	Write data setup time	10	-	ns	
D[17:0],	tdht	Write data hold time	10	-	ns	For movimum CL 20nF
D[17:10]&D[8:1], D[17:10],	trat	Read access time	-	40	ns	For maximum CL=30pF For minimum CL=8pF
D[17:10], D[17:9]	tratfm	Read access time	,	340	ns	For millimum OL=opr
D[17.9]	trod	Read output disable time	20	80	ns	

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7.3 Display Serial Interface Timing Characteristics (3-line SPI system)

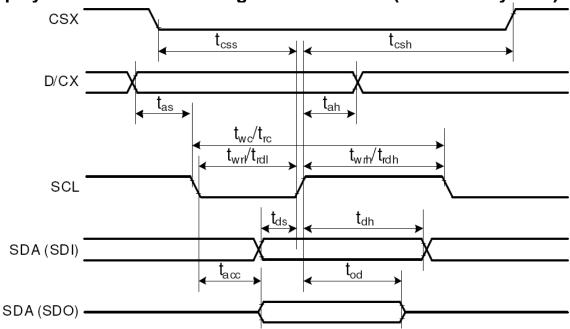


Signal	Symbol	Parameter	min	max	Unit	Description
	tscycw	Serial Clock Cycle (Write)	100	-	ns	
	tshw	SCL "H" Pulse Width (Write)	40	-	ns	
SCL	tslw	SCL "L" Pulse Width (Write)	40	-	ns	
SOL	tscycr	Serial Clock Cycle (Read)	150	-	ns	
	tshr	SCL "H" Pulse Width (Read)	60	-	ns	
	tslr	SCL "L" Pulse Width (Read)	60	-	ns	
SDA / SDI	tsds	Data setup time (Write)	30	-	ns	
(Input)	tsdh	Data hold time (Write)	30	-	ns	
SDA / SDO	tacc	Access time (Read)	10	-	ns	
(Output)	toh	Output disable time (Read)	10	50	ns	
	tscc	SCL-CSX	20	-	ns	
CSX	tchw	CSX "H" Pulse Width	40	-	ns	
CSX	tcss	CSX-SCL Time	60	-	ns	
	tcsh	CSX-SOL TIME	65	-	ns	

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7.4 Display Serial Interface Timing Characteristics (4-line SPI system)

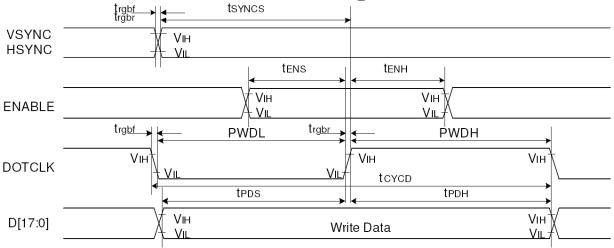


Signal	Symbol	Parameter	min	max	Unit	Description
CSX	tcss	Chip select time (Write)	40	-	ns	
03/	tcsh	Chip select hold time (Read)	40	-	ns	
	twc	Serial clock cycle (Write)	100	-	ns	
	twrh	SCL "H" pulse width (Write)	40	-	ns	
SCL	twrl	SCL "L" pulse width (Write)	40	-	ns	
SCL	trc	Serial clock cycle (Read)	150	-	ns	
	trdh	SCL "H" pulse width (Read)	60	-	ns	
	trdl	SCL "L" pulse width (Read)	60	-	ns	
D/CX	tas	D/CX setup time	10	-		
D/GX	tah	D/CX hold time (Write / Read)	10	-		
SDA / SDI	tds	Data setup time (Write)	30	-	ns	
(Input)	tdh	Data hold time (Write)	30	-	ns	
SDA / SDO	tacc	Access time (Read)	10	-	ns	For maximum CL=30pF
(Output)	tod	Output disable time (Read)	10	50	ns	For minimum CL=8pF

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7.5 Parallel 24/18/16-bit RGB Interface Timing Characteristics

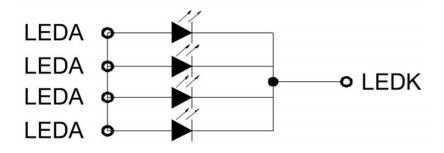


Signal	Symbol	Parameter	min	max	Unit	Description
VSYNC /	t _{SYNCS}	VSYNC/HSYNC setup time	15	-	ns	
HSYNC	t _{SYNCH}	VSYNC/HSYNC hold time	15	-	ns	
DE	t _{ENS}	DE setup time	15	-	ns	
DE	t _{ENH}	DE hold time	15	1	ns	
D[17:0]	t _{POS}	Data setup time	15	-	ns	18/16-bit bus RGB
D[17.0]	t _{PDH}	Data hold time	15	-	ns	interface mode
	PWDH	DOTCLK high-level period	15	-	ns	
DOTCLK	PWDL	DOTCLK low-level period	15	-	ns	
DOTCER	tcycD	DOTCLK cycle time	100	-	ns	
	t _{rgbr} , t _{rgbf}	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns	
VSYNC /	tsyncs	VSYNC/HSYNC setup time	15	-	ns	
HSYNC	t _{SYNCH}	VSYNC/HSYNC hold time	15	-	ns	
DE	t _{ENS}	DE setup time	15	ı	ns	
DE	t _{ENH}	DE hold time	15	-	ns	
D[47.0]	t _{POS}	Data setup time	15	ı	ns	6-bit bus RGB
D[17:0]	t _{PDH}	Data hold time	15	-	ns	interface mode
	PWDH	DOTCLK high-level pulse period	15		ns	
DOTCLK	PWDL	DOTCLK low-level pulse period	15	1	ns	
DOTOLK	tcycp	DOTCLK cycle time	100	-	ns	
	t _{rgbr} , t _{rgbf}	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns	

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8. Backlight Characteristics



BACKLIGHT CIRCUIT

Item	Symbol	MIN	TYP	MAX	UNIT	Test Condition
Supply Voltage	Vf	2.9	3.2	3.5	V	If=80mA
Supply Current	lf		80		mA	
Luminous Intensity for LCM		200	300		Cd/m ²	If=80mA
Uniformity for LCM		80			%	If=80mA
Life Time		20000			Hr	If=80mA
Backlight Color	White					



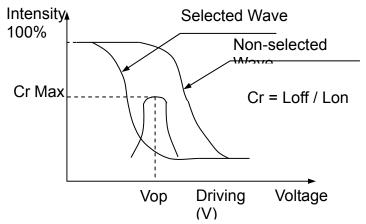
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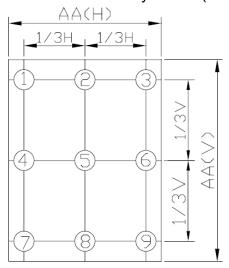
9. Optical Characteristics

ITEM		SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT	REMARK
Brightness		BL	θ =φ= 0°	200	300		cd/m²	Note2
Contrast I	Ratio	CR	$\theta = \phi = 0^{\circ}$		300			Note3
Response	Time	Tr+ Tf	θ =φ= 0°		30	-	ms	Note4
	Upper	Φ			45	I	I	
Viewing	Down	U	CD > 10		20	-		Note 5 Note 6
Angle	Right		CR≧10		45			
	Left	φ			45			
	White	Х	θ =φ= 0°		0.297			
	VVIIILE	у			0.327	Typ. +0.05		
	Red	X	$\theta = \phi = 0^{\circ}$		0.631			
Color Filter	Neu	У	υ –ψ- υ	Тур.	0.316			
Chromaticity	Green	Χ	θ =φ= 0°	-0.059	0.298			
	Gibbli	у	υ –ψ= υ		0.566		1	
	Blue	Χ	θ =φ= 0°		0.138			
	Diue	у	υ –ψ– υ		0.122			

Note1: Definition of Operation Voltage (Vop)



Note2: Definition of Luminance Uniformity: L = L(MIN) / L (MAX) × 100%

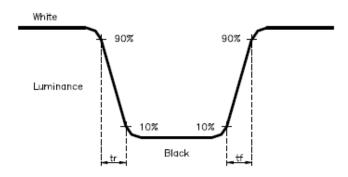


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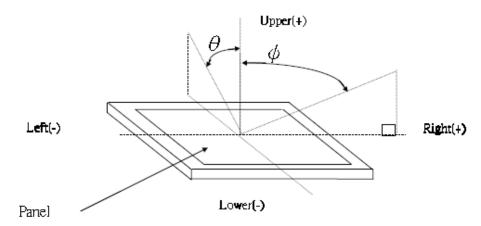
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Note 3. Definition of Contrast Ratio: CR = White Luminance (ON) / Black Luminance (OFF)

Note 4. Definition of response time: The response time is defined as the time interval between the 10% and 90% amplitudes.



Note 5. Definition of view angle($\theta \cdot \psi$):



Note 6. Light source: Clight.



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10. Reliability Test Conditions and Methods

No change on display and in operation under the following test condition.

Condition: Unless otherwise specified, tests will be conducted under the following condition.

Temperature: 20±5°C Humidity: 65±5%RH Tests will be not conducted under functioning state.

No.	Parameter	Condition	Notes
1	High Temperature Operating	70°C±2°C, 96hrs (Operation state)	
2	Low Temperature Operating	-20°C±2°C, 96hrs (Operation state)	
3	High Temperature Storage	80°C±2°C, 96hrs	
4	Low Temperature Storage	-30°C±2°C, 96hrs	
5	High Temperature and High Humidity Operation Tes t	60°C±2°C, 90%, 96hrs	
6	Vibration Test	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 direction of X, Y, Z each 15 minutes.	
7.	Drop Test	To be measured after dropping from 60cm high on the concrete surface in packing state. F Dropping method corner dropping A corner: once Edge dropping B, C, D edge: once Face dropping E, F, G face: once Concrete Surface	

Notes:

- 1. No dew condensation to be observed.
- 2. The function test shall be conducted after 4 hours storage at the normal temperature and humidity after removed from the test chamber.
- 3. Vibration test will be conducted to the product itself without putting I in a container.



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11. Inspection Standard

11.1.1 Inspection conditions

Inspection performed under the following conditions is recommended.

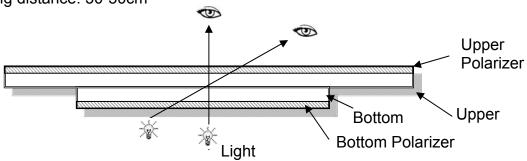
Temperature: 25±5°C

Humidity: 65%±10%RH

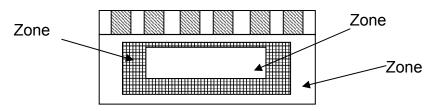
Viewing Angle: Normal viewing Angle.

Illumination: Single fluorescent lamp (300 to 700Lux)

Viewing distance: 30-50cm



11.1.2 Definition



Zone A: Effective Viewing Area (Character or Digit can be seen)

Zone B: Viewing Area except Zone A

Zone C: Outside (Zone A + Zone B) which cannot be seen after assembly by customer.)

Note:

As a general rule, visual defects in Zone C can be ignored when it doesn't effect product function or appearance after assembly by customer.

11.1.3 Sampling Plan

According to GB/T 2828-2003; normal inspection, Class $\scriptstyle \rm II$ AQL:

Major defect	Minor defect
0.65	1.5

LCD: Liquid Crystal Display, TP: Touch Panel, LCM: Liquid Crystal Module

No	Items to be inspected	Criteria	Classification of defects
1	Functional defects	 No display, Open or miss line Display abnormally, Short Backlight no lighting, abnormal lighting. TP no function 	Major
2	Missing	Missing component	Wajoi
3	Outline dimension	Overall outline dimension beyond the drawing is not allowed	



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4	Color tone	Color unevenness, refer to limited sample	
5	Soldering appearance	Good soldering, Peeling off is not allowed.	Minor
6	LCD/Polarizer/TP	Black/White spot/line, scratch, crack, etc.	

11.1.4 Criteria (Visual)

11.1.4 Criteria (Visual)								
Number	Items	Criteria(mm)						
	(1) The edge of LCD broken							
		X Y Z ≤3.0mm						
1.0 LCD Crack / Broken NOTE: X: Length Y: Width Z: Height L: Length of ITO, T: Height of LCD	(2)LCD corner broken	X Y Z ≤3.0mm ≤L ≤T						
	(3) LCD crack	Crack Not allowed						



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Number	Items	Criteria (mm)						
		① light dot (LCD	/TP/Polarizer	black/white	spot , light do	t, pinhole,		
		dent, stain)						
		Zone	Ac	ceptable Qt	У			
		Size (mm)	Α	В	С			
		Ф≤0.10	Ignore					
		0.10<Φ≤0.15	3(distance	≧10mm)	Ignore			
		0.15<Φ≤0.2	1		ignore			
		0.2<Ф	0					
	Spot defect	②Dim spot(LCI	D/TP/Polarize	r dim dot, lig	ht leakage、	dark spot)		
	✓ ↑	Zone	Ac	ceptable Qt	у			
		Size (mm)	Α	В	С			
		Ф≤0.1	Igno	re				
	← → X	0.1<Φ≤0.2	2(distance≥10mm)		Ignore			
	Ф=(X+Y)/2	0.2<Φ≤0.3	1		ignore			
2.0		Ф>0.3	0					
		③ Polarizer accidented spot						
		Zone	Acceptable Q		ty			
		Size (mm)	А	В	С			
		Ф≤0.2	Igno	ore				
		0.2<Φ≤0.5	2(distance ≥ 10mm)		Ignore			
		Ф>0.5	0		-			
						•		
		VAC -III- ()	Length(m	Accept	able Qty			
	Line defect	Width(mm)	m) `	A E	3 C			
	(LCD/TP /Polarizer	Ф≤0.03	Ignore	Ignore				
	black/white line, scratch, stain)	0.03 <w≤0.05< td=""><td>L≤3.0</td><td>N≤2</td><td>Ignore</td><td></td></w≤0.05<>	L≤3.0	N≤2	Ignore			
		0.05 <w≤0.08< td=""><td>L≤2.0</td><td>N≤2</td><td></td><td></td></w≤0.08<>	L≤2.0	N≤2				
		0.08 <w< td=""><td colspan="3">Define as spot defect</td><td></td></w<>	Define as spot defect					
						•		



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		Zone	,	Acceptable C	Qty		
		Size (mm)	Α	В	С		
3.0	Polarizer	Ф≤0.2	lgr	nore			
3.0	Bubble	0.2\\$\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	1				
		0.4<Φ≤0.6		1	Ignore	nore	
		0.6<Ф	0		r.		
4.0	SMT	According to IPC-A-610C class II standard. Function defect missing part are major defect, the others are minor defect.					



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12. Handling Precautions

12.1 Mounting method

The LCD panel of AMSON TFT module consists of two thin glass plates with polarizes which easily be damaged. And since the module in so constructed as to be fixed by utilizing fitting holes in the printed circuit board.

Extreme care should be needed when handling the LCD modules.

12.2 Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent

[Recommended below] and wipe lightly

- Isopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns Do not use the following solvent on the pad or prevent it from being contaminated:

- Soldering flux
- Chlorine (CI), Sulfur (S)

If goods were sent without being silicon coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happen by miss-handling or using some materials such as Chlorine (CI), Sulfur (S) from customer, Responsibility is on customer.

12.3 Caution against static charge

The LCD module use C-MOS LSI drivers, so we recommended that you:

Connect any unused input terminal to VDD or GND, do not input any signals before power is turned on, and ground your body, work/assembly areas, and assembly equipment to protect against static electricity.

12.4 packing

- Module employs LCD elements and must be treated as such.
- Avoid intense shock and falls from a height.
- To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity

12.5 Caution for operation

- It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life.
- An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.
- Response time will be extremely delayed at lower temperature then the operating temperature range and on the other hand at higher temperature LCD's how dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operation temperature.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- Slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.
 - Usage under the maximum operating temperature, 50%Rh or less is required.



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2018-09-05

12.6 storing

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

- Storage in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it. And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.
- Storing with no touch on polarizer surface by the anything else.
 [It is recommended to store them as they have been contained in the inner container at the time of delivery from us.

12.7 Safety

- It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.
- When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

13. Precaution for Use

13.1

A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

13.2

On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

- When a question is arisen in this specification.
- When a new problem is arisen this is not specified in this specification.
- When an inspection specifications change or operating condition change in customer is reported to AMSON TFT and some problem is arisen in this specification due to the change.
- When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

14. Packing Method

TBD